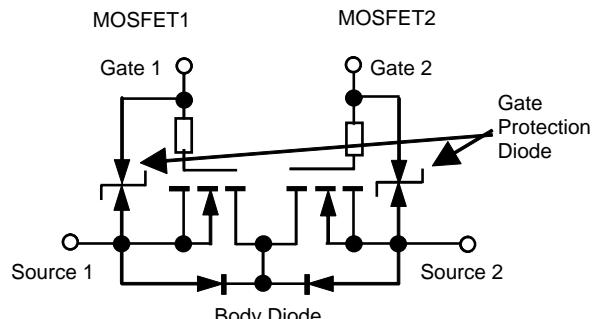


## WNMD2171

**Dual N-Channel, 20V, 6A, Power MOSFET**

[www.sh-willsemi.com](http://www.sh-willsemi.com)

<b>V<sub>SSS</sub> (V)</b>	<b>Typ R<sub>SS(on)</sub> (mΩ)</b>
20	36@ V <sub>GS</sub> =4.5V
	38@ V <sub>GS</sub> =3.8V
	41@ V <sub>GS</sub> =3.1V
	43@ V <sub>GS</sub> =2.5V
ESD Rating:2000V HBM	



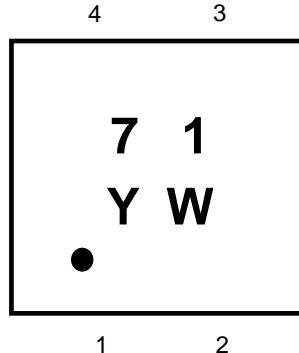
## Descriptions

The WNMD2171 is Dual N-Channel enhancement MOS Field Effect Transistor and connecting the Drains on the circuit board is not required because the Drains of the MOSFET1 and the MOSFET2 are internally connected. Uses advanced trench technology and design to provide excellent R<sub>SS(ON)</sub> with low gate charge. This device is designed for Lithium-Ion battery protection circuit. The WNMD2171 is available in CSP-4L package. Standard Product WNMD2171 is Pb-free and Halogen-free.

## Features

- Trench Technology
- Supper high density cell design
- Excellent ON resistance for higher DC current
- Extremely Low Threshold Voltage
- Small package CSP 4L

**CSP 4L**



- |             |    |               |
|-------------|----|---------------|
| 1: Source 1 | 71 | = Device Code |
| 2: Gate 1   | Y  | = Year        |
| 3: Gate 2   | W  | = Week (A~Z)  |
| 4: Source 2 |    |               |

**Pin configuration (TOP view) & Marking**

## Order information

## Applications

- Lithium-Ion battery protection circuit

Device	Package	Shipping
WNMD2171-4/TR	CSP 4L	3000/Reel&Tape

**Electronics Characteristics (Ta=25°C, unless otherwise noted)**

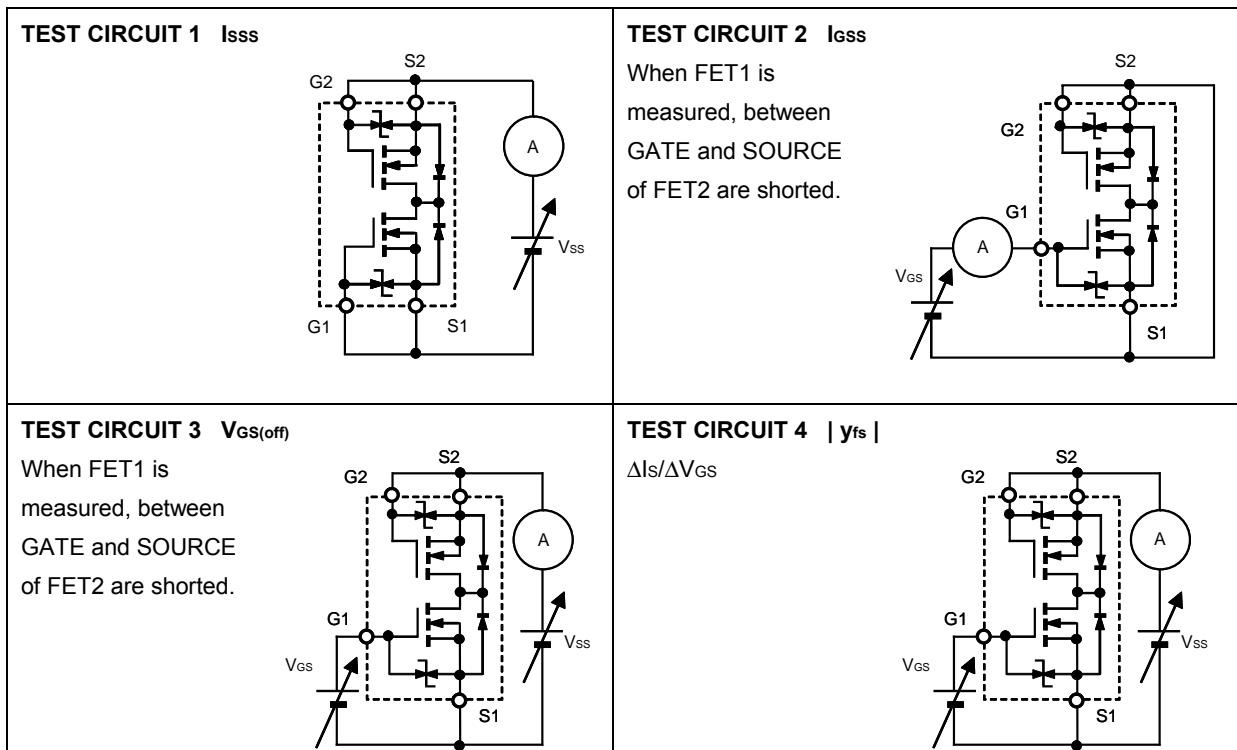
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS</b>						
Source to Source Voltage	V <sub>SSS</sub>	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 250uA	20			V
Zero Gate Voltage Drain Current	I <sub>SSS</sub>	V <sub>SS</sub> =16 V, V <sub>GS</sub> = 0V TEST CIRCUIT 1			1	uA
Gate Leakage Current	I <sub>GSS</sub>	V <sub>SS</sub> = 0 V, V <sub>GS</sub> = ±12V TEST CIRCUIT 2			±10	uA
<b>ON CHARACTERISTICS</b>						
Gate to Source Cut-off Voltage	V <sub>GS(off)</sub>	V <sub>GS</sub> = V <sub>SS</sub> , I <sub>S</sub> = 250uA TEST CIRCUIT 3	0.4	0.74	1.0	V
Source to Source On-state Resistance	R <sub>SS(on)</sub>	V <sub>GS</sub> = 4.5V, I <sub>S</sub> = 3.0A TEST CIRCUIT 5	17	36	45	mΩ
		V <sub>GS</sub> = 3.8V, I <sub>S</sub> = 3.0A TEST CIRCUIT 5	18	38	47	
		V <sub>GS</sub> = 3.1V, I <sub>S</sub> = 3.0A TEST CIRCUIT 5	19	41	54	
		V <sub>GS</sub> = 2.5V, I <sub>S</sub> = 3.0A TEST CIRCUIT 5	21	43	65	
Forward Transfer Admittance	yfs	V <sub>SS</sub> = 10 V, I <sub>S</sub> = 1.8A TEST CIRCUIT 4		11		S
<b>CHARGES, CAPACITANCES AND GATE RESISTANCE</b>						
Input Capacitance	C <sub>ISS</sub>	V <sub>GS</sub> = 0 V, f = 1kHz, V <sub>SS</sub> = 10 V TEST CIRCUIT 7		1210		pF
Output Capacitance	C <sub>OSS</sub>			149		
Reverse Transfer Capacitance	C <sub>RSS</sub>			135		
Total Gate Charge	Q <sub>G(TOT)</sub>	V <sub>G1S1</sub> = 4.5 V, V <sub>SS</sub> = 10V, I <sub>S</sub> =6A TEST CIRCUIT 9		15.6		nC
Threshold Gate Charge	Q <sub>G(TH)</sub>			1.15		
Gate-to-Source Charge	Q <sub>GS</sub>			2.8		
Gate-to-Drain Charge	Q <sub>GD</sub>			3.8		
<b>SWITCHING CHARACTERISTICS</b>						
Turn-On Delay Time	td(ON)	V <sub>GS</sub> = 4.5 V, V <sub>SS</sub> =10V, I <sub>S</sub> =5.0A, R <sub>G</sub> =6Ω TEST CIRCUIT 8		410		ns
Rise Time	tr			1200		
Turn-Off Delay Time	td(OFF)			6100		
Fall Time	tf			3500		
<b>BODY DIODE CHARACTERISTICS</b>						
Body Diode Forward Voltage	V <sub>F(S-S)</sub>	V <sub>GS</sub> = 0 V, I <sub>F</sub> = 1.0A TEST CIRCUIT 6			1.5	V

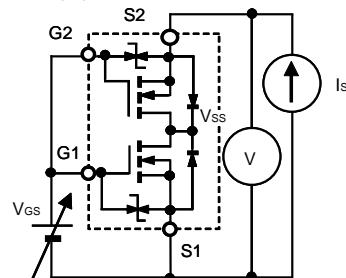
## Absolute Maximum ratings

Parameter	Symbol	10 s	Steady State	Unit
Source to Source Voltage ( $V_{GS} = 0 \text{ V}$ )	$V_{SSS}$	20	$\pm 12$	V
Gate to Source Voltage ( $V_{SS} = 0 \text{ V}$ )	$V_{GSS}$			
Source Current (pulse) <sup>Note.c</sup>	$I_{S(\text{pulse})}$	60	A	
Source Current (DC)	$I_S$	6	A	
Channel Temperature	$T_{ch}$	150		°C
Storage Temperature Range	$T_{stg}$	-55 to 150		°C

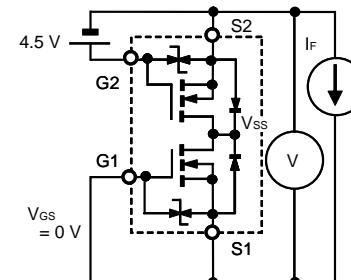
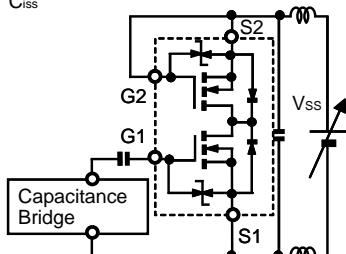
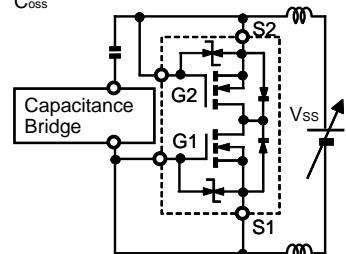
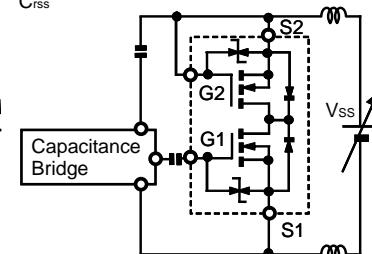
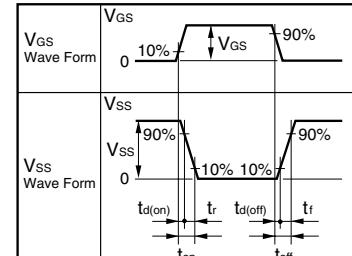
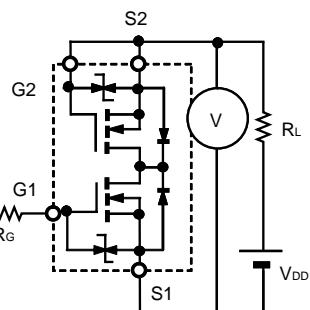
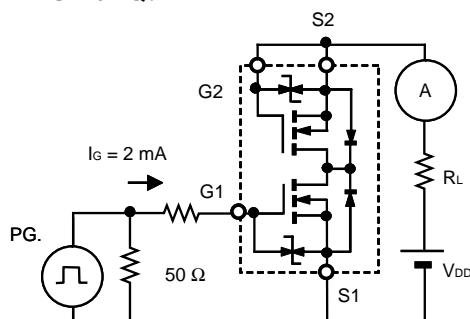
Note.c PW≤10μs, duty cycle≤1%;

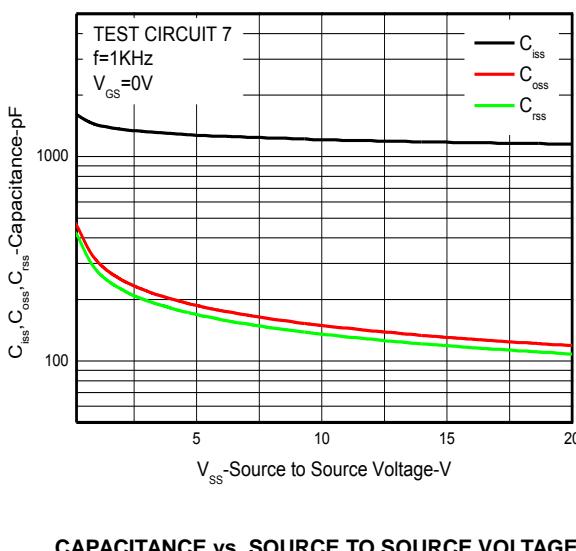
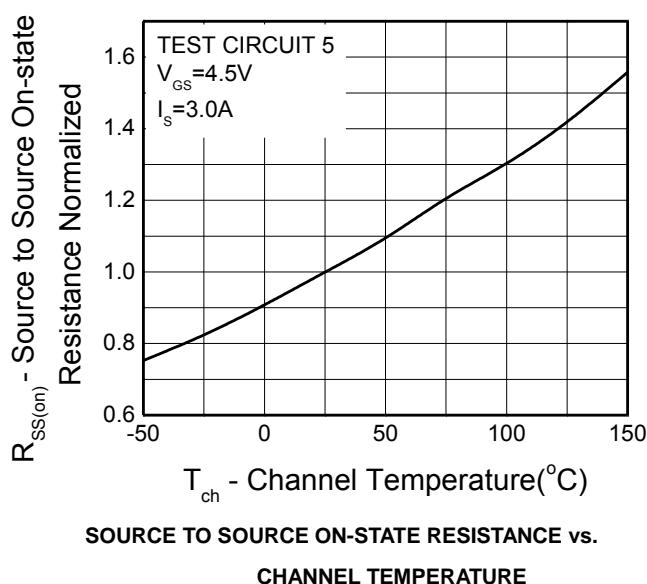
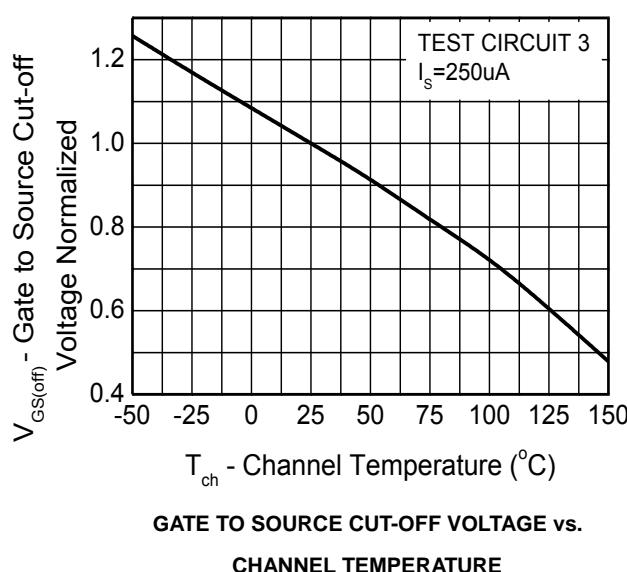
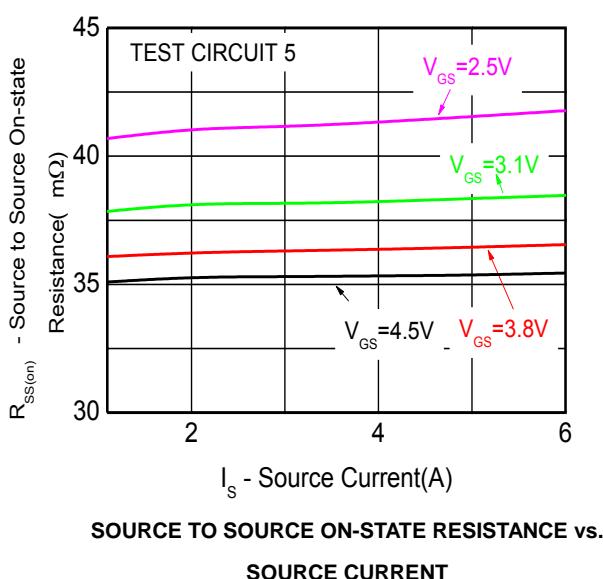
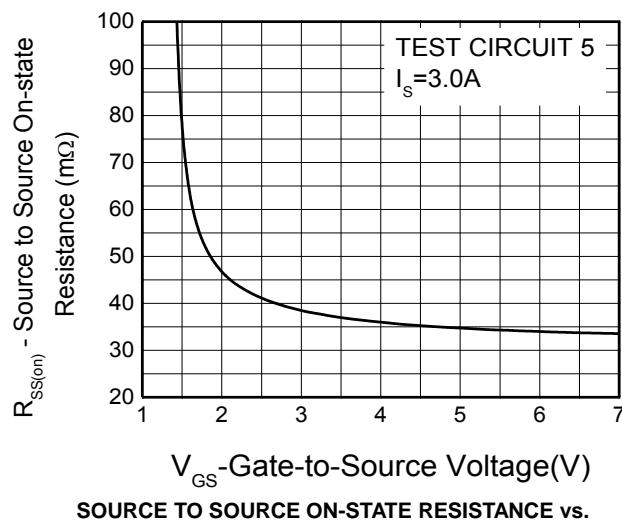
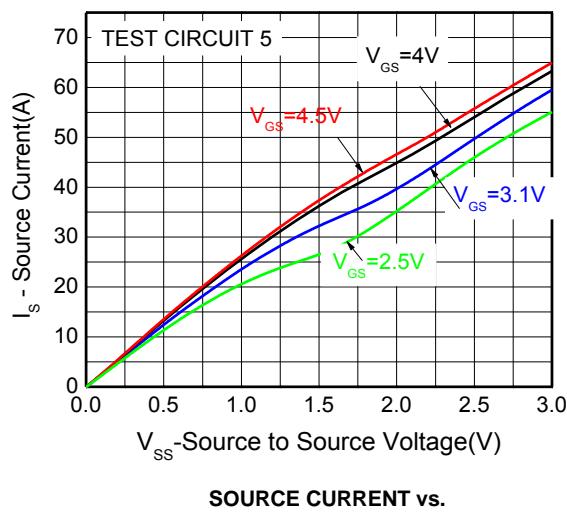
Both the FET1 and the FET2 are measured. Test circuits are example of measuring the FET1 side.

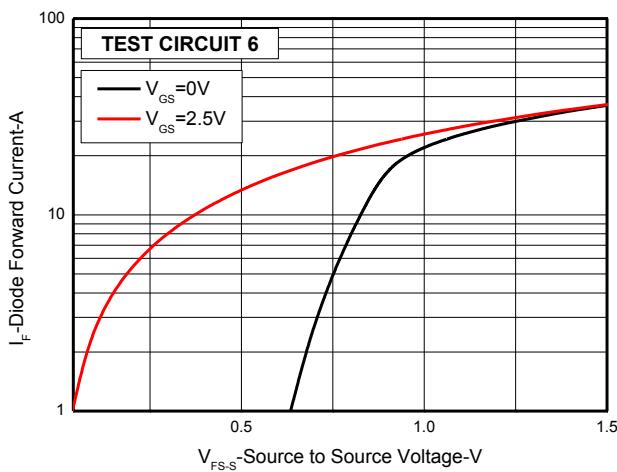


**TEST CIRCUIT 5  $R_{SS(on)}$** 
 $V_{SS}/I_S$ 

**TEST CIRCUIT 6  $V_{F(S-S)}$** 

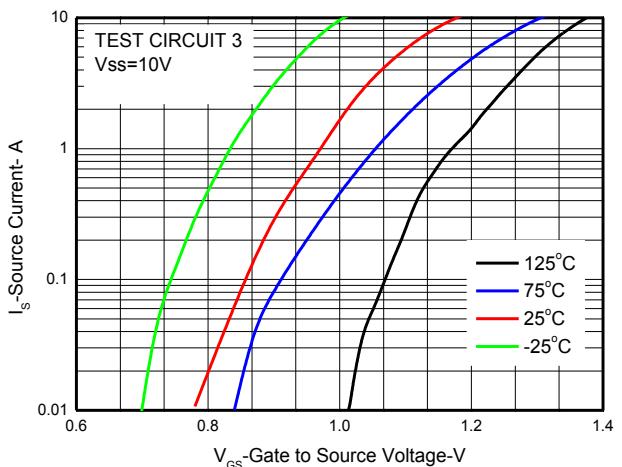
When FET1 is measured,  
FET2 is added  $V_{GS} + 4.5$  V.


**TEST CIRCUIT 7**
 $C_{iss}$ 

 $C_{oss}$ 

 $C_{rss}$ 

**TEST CIRCUIT 8  $t_{d(on)}, t_r, t_{d(off)}, t_f$** 

**TEST CIRCUIT 9  $Q_G$** 


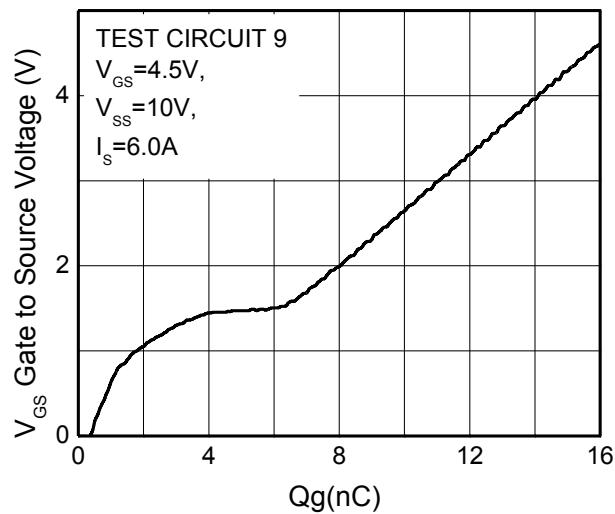
**Typical Characteristics ( $T_a=25^\circ\text{C}$ , unless otherwise noted)**




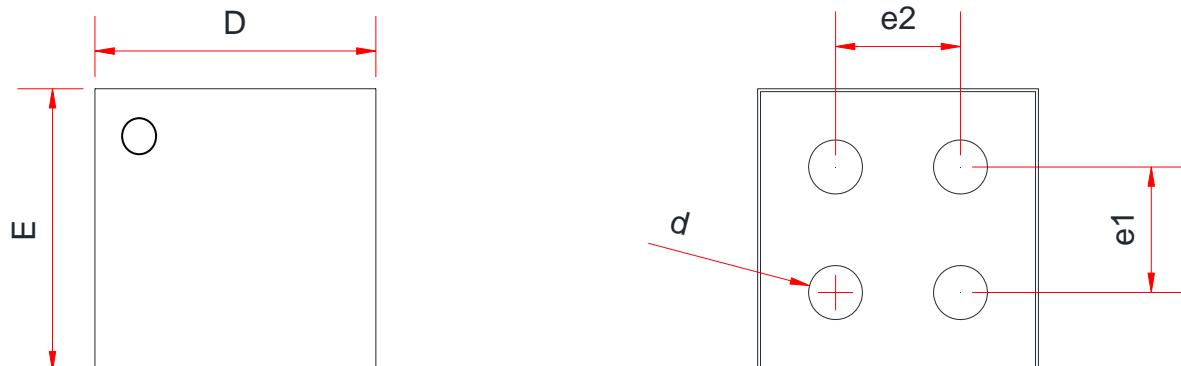
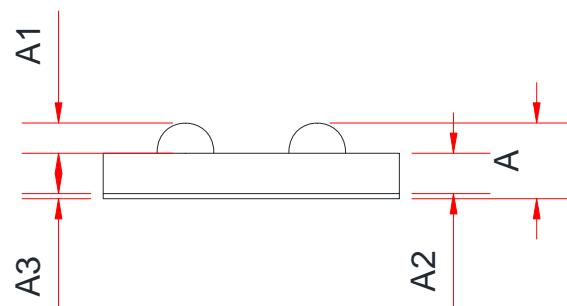
SOURCE TO SOURCE DIODE FORWARD VOLTAGE



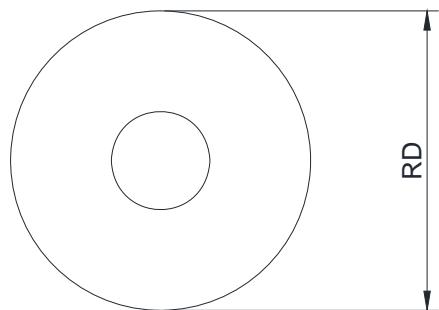
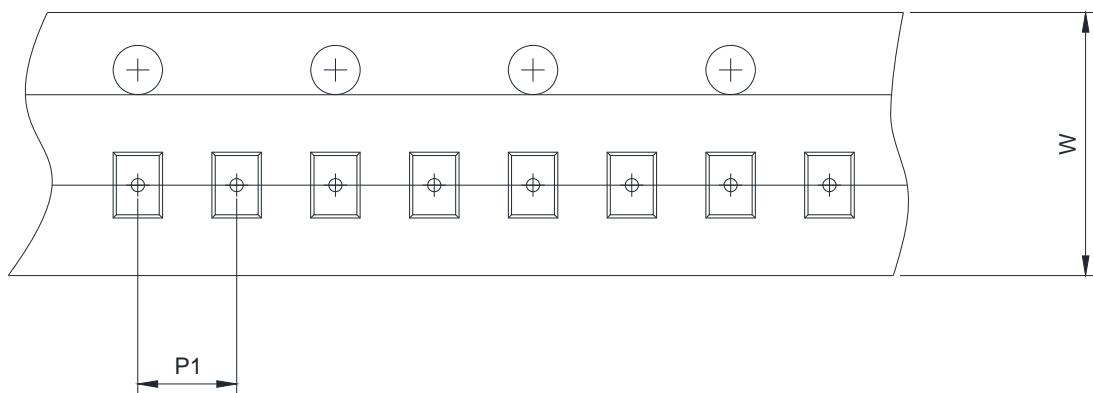
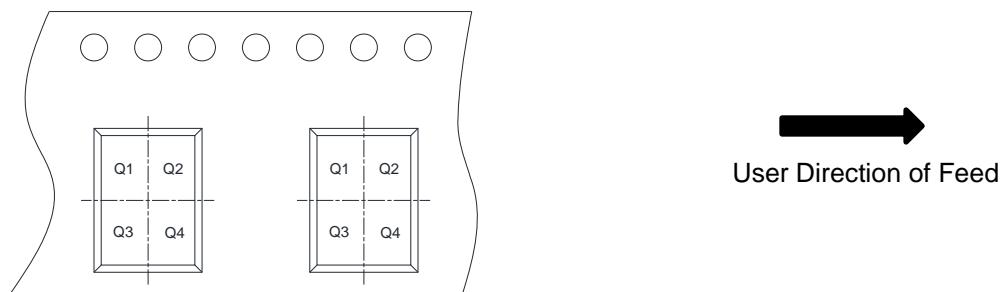
FORWARD TRANSFER CHARACTERISTICS



DYNAMIC INPUT CHARACTERISTICS

**PACKAGE OUTLINE DIMENSIONS**
**WLCSP-4L**

**TOP VIEW**
**BOTTOM VIEW**

**SIDE VIEW**

Symbol	Dimensions in Millimeters		
	Min.	Typ.	Max.
A	0.282	0.315	0.348
A1	0.075	0.090	0.105
A2	0.187	0.200	0.213
A3	0.020	0.025	0.030
D	1.450	1.470	1.490
E	1.450	1.470	1.490
e1		0.650 Typ.	
e2		0.650 Typ.	
d	0.280	0.300	0.320

**TAPE AND REEL INFORMATION**
**Reel Dimensions**

**Tape Dimensions**

**Quadrant Assignments For PIN1 Orientation In Tape**


<b>RD</b>	<b>Reel Dimension</b>	<input checked="" type="checkbox"/> 7inch <input type="checkbox"/> 13inch
<b>W</b>	<b>Overall width of the carrier tape</b>	<input checked="" type="checkbox"/> 8mm <input type="checkbox"/> 12mm <input type="checkbox"/> 16mm
<b>P1</b>	<b>Pitch between successive cavity centers</b>	<input type="checkbox"/> 2mm <input checked="" type="checkbox"/> 4mm <input type="checkbox"/> 8mm
<b>Pin1</b>	<b>Pin1 Quadrant</b>	<input checked="" type="checkbox"/> Q1 <input type="checkbox"/> Q2 <input type="checkbox"/> Q3 <input type="checkbox"/> Q4